SDLS147 - SEPTEMBER 1972 - REVISED MARCH 1988

- Three-State Version of SN54/74LS153, SN54/74S153
- Schottky-Diode-Clamped Transistors
- Permits Multiplexing from N Lines to 1 Line
- Performs Parallel-to Serial Conversion
- Fully Compatible with Most TTL Circuits

description

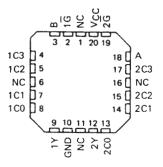
Each of these Schottky-clamped data selectors/multiplexers contains inverters and drivers to supply fully complementary, on-chip, binary decoding data selection to the AND-OR gates. Separate output control inputs are provided for each of the two four-line sections.

The three-state outputs can interface with and drive data lines of bus-organized systems. With all but one of the common outputs disabled (at a high-impedance state) the low-impedance of the single enabled output will drive the bus line to a high or low logic level. SN54LS253, SN54S253 . . . J OR W PACKAGE SN74LS253, SN74S253 . . . D OR N PACKAGE

(TOP VIEW)

1G [ſī	U ₁₆	Vcc
в	2	15	2Ġ
1C3 [3	14	Α
1C2 [4	13	2C3
1C1	15	12	2C2
1C0 [6	11	2C1
1Y [17	10	2C0
GND [8	9	2Y

SN54LS253, SN54S253... FK PACKAGE (TOP VIEW)



NC-No internal connection

			F	UNCTIO	ON TAB	LE		
		ECT		DATA	INPUTS	OUTPUT	ουτρυτ	
	В	Α	CO	C1	C2	C3	Ğ	Y
	X	х	×	х	X	Х	н	Z
	L	L	L	х	X	х	L	L
1	L	L	н	×	×	X	L	н
	L	н	×	L	×	Х	L	L
	Ĺ	н	X	н	×	Х	L	н
	н	L	X	×	L	Х	L	L
	н	L	×	х	н	х	L	н
ĺ	н	н	×	х	×	L	L	L
	н	н	x	х	х	н	L	н

Address inputs A and B are common to both sections.

H = high level, L = low level, X = irrelevant, Z = high impedance (off)

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Input voltage: 'LS253		7V
'S253		5.5 V
Off-state output voltage		5.5 V
Operating free-air temperature range:	SN54LS253, SN54S253	
	SN74LS253, SN74S253	0°C to 70°C
Storage temperature range		– 65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

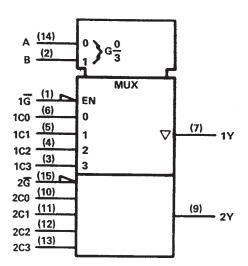
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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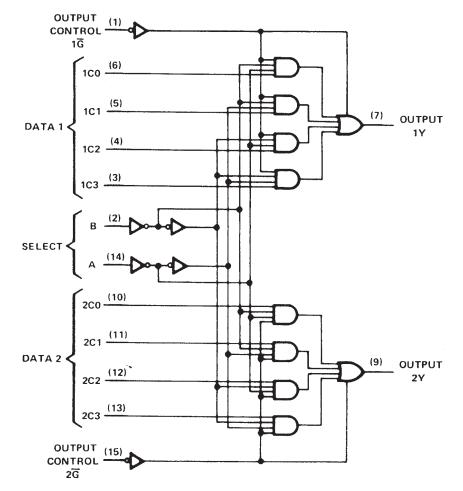
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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

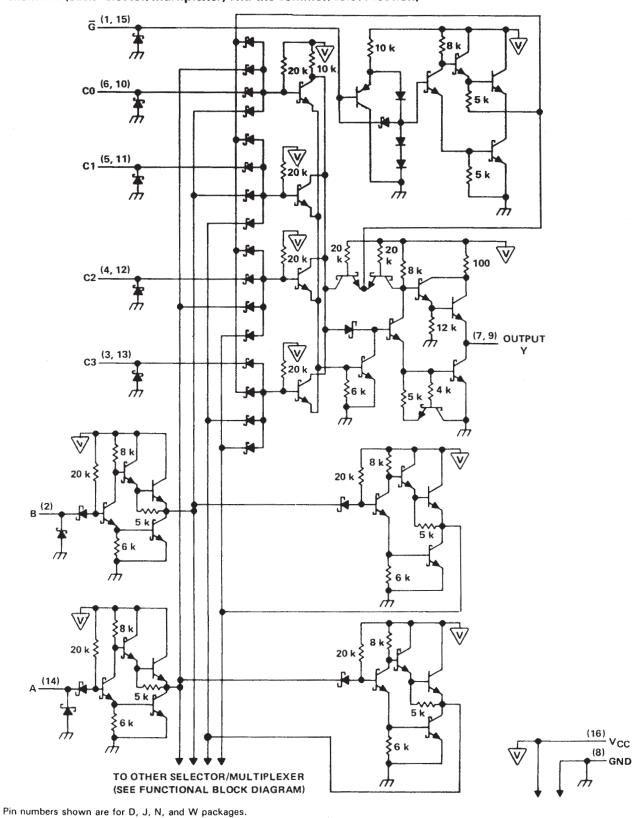
logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.



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schematic (each selector/multiplexer, and the common select section)

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recommended operating conditions

		S	N54LS2	:53	S	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
юн	High-level output current			- 1			- 2.6	mA
IOL	Low-level output current			4			8	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITI	onst		S	N54LS2	53	S	N74LS2	53	
PANAMETEN		IEST CONDITI		MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT	
VIK	V _{CC} = MIN,	lj = - 18 mA					- 1.5			- 1.5	V
VOH	V _{CC} = MIN,	V _{IH} = 2 V,	VIL = MAX,	IOH = MAX	2.4	3.4		2.4	3.1		v
VOL	Vcc = MIN,	N		IOL = 4 mA		0.25	0.4		0.25	0.4	v
VOL	VCC - WIN,	V _{IH} = 2 V,	VIL = MAX	IOL = 8 mA					0.25	0.5	
loz	V _{CC} = MAX,	VIH = 2 V		V ₀ = 2.7 V			20			20	
102	VCC - MAX,	5 - MAA, VIH - 2 V		V ₀ = 0.4 V			- 20			- 20	μA
1	V _{CC} = MAX,	V ₁ = 7 V					0.1			0.1	mA
ін	$V_{CC} = MAX,$	VI = 2.7 V					20			20	μA
1	Vcc = MAX,	V1 = 0.4 V		G	1		- 0.2			- 0.2	
<u>н</u> г	VCC - MAX,	vj = 0.4 v		All other			- 0.4			- 0.4	_ mA
IOS§	V _{CC} = MAX				- 30		- 130	- 30		- 130	mA
Icc		CC = MAX, See Note 2		Condition A		7	12		7	12	
100		See Note 2		Condition B		8.5	14		8.5	14	mA

[†] For conditions shown as MIN or MAX, use the appropriate value spcified under recommended operating conditions.

[‡] All typical values are at $V_{CC} = 5 V$, $T_A = 25^{\circ}C$.

§ Not more than one output should be shorted at a time, and duration for the short-circuit should exceed one second.

NOTE 2: I_{CC} is measured with the outputs open under the following conditions:

A. All inputs grounded.

B. Output control at 4.5 V, all inputs grounded.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	түр	мах	UNIT
tPLH	Data	Y			17	25	
t PHL	Data	T			13	20	ns
^t PLH	Select	Y	$C_{L} = 15 \text{ pF}, \qquad R_{L} = 2 \text{ k}\Omega,$		30	45	
^t PHL	Delect		See Note 3		21	32	ns
^t PZH	Output	Y	×		15	28	
^t PZL	Control				15	23	ns
^t PHZ	Output	v	$C_L = 5 pF$, $R_L = 2 k\Omega$,		27	41	
^t PLZ	Control		See Note 3		18	27	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



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recommended operating conditions

		S	N54S25	53	S	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
v _{cc}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	v
юн	High-level output current	· · · · · · · · · · · · · · · · · · ·		- 2			- 6.5	mA
IOL	Low-level output current			20			20	mA
TA	Operating free-air temperature	- 55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDIT	TIONST		MIN	TYP [‡]	MAX	UNIT
VIK	V _{CC} = MIN,	l ₁ = - 18 mA						- 1.2	V
VOH	Vcc = MIN,	V1H = 2 V,	VIL = 0.8 V,		Series 54S	2.5	3.4		v
•04	VCC - WIIN,	VIH - 2 V,	VIL - 0.8 V,	IOH = MAX	Series 74S	2.7	3.4		
VOL	VCC = MIN,	VIH = 2 V,	VIL = 0.8 V,	IOL = 20 mA				0.5	V
loz	V _{CC} = MAX,	Viн = 2 V			V ₀ = 2.4 V			50	
.02		VIH - 2 V			V _O = 0.5 V			- 50	μΑ
11	$V_{CC} = MAX,$	VI = 5.5 V						1	mA
ін	V _{CC} = MAX,	VI = 2.7 V						50	μA
μL	Vcc = MAX,				<u>G</u> = 0.8 V			- 2	
	VCC-WAX,	VI = 0.5 V			<u>G</u> = 2 V			- 0.25	mA
IOS§	V _{CC} = MAX				4	- 40		- 100	mA
lcc	V _{CC} = MAX,	See Note 2	ann an		Condition A		45	70	
		See Note 2			Condition B		65	85	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. \ddagger All typical values are at V_{CC} = 5 V, T_A = 25°C.

Not more than one output should be shorted at a time and duration of short-circuit should not exceed one second. NOTE 2: I_{CC} is measured with the outputs open under the following conditions:

A. All inputs grounded.

B. Output control at 4.5 V, all inputs grounded.

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

PARAMETER	FROM TO (INPUT) (OUTPUT)		TEST CON	TEST CONDITIONS			UNIT	
^t PLH	Data	~	· · · · · · · · · · · · · · · · · · ·		6	9		
^t PHL	Data	T			6	9	ns	
^t PLH	Select Y	×	RL = 280 Ω, See Note 3	CL = 15 pF	11.5	18		
^t PHL					12	18	ns	
^t PZH	Output	v			11	16.5		
^t PZL	Control	r			12	18	ns	
^t PHZ	Output	×	R _L = 280 Ω,	CL = 5 pF	6.5	9.5		
^t PLZ	Control	1	See Note 3	See Note 3			ns	

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
76017012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	76017012A SNJ54LS 253FK	Samples
7601701EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601701EA SNJ54LS253J	Samples
7601701EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601701EA SNJ54LS253J	Samples
JM38510/30908BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BEA	Samples
JM38510/30908BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BEA	Samples
JM38510/30908BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BFA	Samples
JM38510/30908BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BFA	Samples
M38510/30908BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BEA	Samples
M38510/30908BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BEA	Samples
M38510/30908BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BFA	Samples
M38510/30908BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30908BFA	Samples
SN54LS253J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS253J	Samples
SN54LS253J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS253J	Samples
SN74LS253DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS253	Samples
SN74LS253DR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS253	Samples
SN74LS253N	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS253N	Samples
SN74LS253N	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS253N	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS253FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	76017012A SNJ54LS 253FK	Samples
SNJ54LS253FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	76017012A SNJ54LS 253FK	Samples
SNJ54LS253J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601701EA SNJ54LS253J	Samples
SNJ54LS253J	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7601701EA SNJ54LS253J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54LS253, SN74LS253 :

• Catalog : SN74LS253

Military : SN54LS253

NOTE: Qualified Version Definitions:

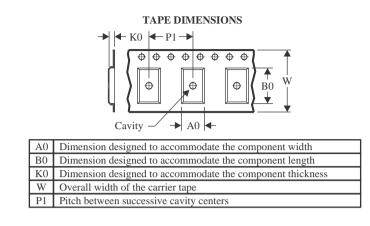
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



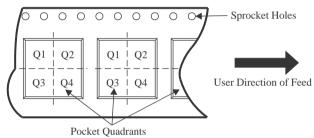
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS253DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



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PACKAGE MATERIALS INFORMATION

9-Aug-2022



*All dimensions are nominal

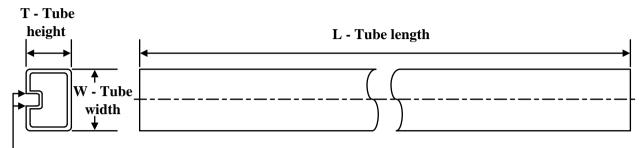
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS253DR	SOIC	D	16	2500	340.5	336.1	32.0

TEXAS INSTRUMENTS

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TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
76017012A	FK	LCCC	20	1	506.98	12.06	2030	NA
JM38510/30908BFA	W	CFP	16	1	506.98	26.16	6220	NA
M38510/30908BFA	W	CFP	16	1	506.98	26.16	6220	NA
SN74LS253N	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS253N	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS253FK	FK	LCCC	20	1	506.98	12.06	2030	NA

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP2-F16



FK 20

8.89 x 8.89, 1.27 mm pitch

GENERIC PACKAGE VIEW

LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



4211283-4/E 08/12

D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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